000	aterial Compositi Copyright 2005. IPC, E rnational and Pan-Am	Bannockbu	urn, Illinois. Al	ll rights reserved utions.	under both	This docume level parts, t	ent is a declarat	ion of the su encompasse	ubstances s all lower	within the manufactur r level materials for wi	er listed it hich the m	em. Note:	if the item is an as r has engineering	sembly with low responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
upplier Information	1													
Company name* Company unique ID						Unique ID Authority				Response Date*				
nsemi											2024-04-	17		
Contact Name			Title - Contact				Phone - Contact*			Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Repres	Title - Representative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards			Product Envir	o Compliance	ance NA Product-Env-Stewards@onsemi.					m				
Requester Item	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Date Version Manufacturing Sit		Anufacturing Site	v	Veight*	UOM	Unit Type		
		MT9V126	6IA3XTC-TR	VGA 1/4 SOC			2024-04-17		Т	TWU	1	86.0	mg	Each
Ianufacturing Proc	cess Information						1		I					
Terminal Plating / Grid Array Material Terminal Base Alloy			J-STD-020 MS	L Rating	Peak Proc	ess Body T	emperatur	e Max Time at Peak	Temperatu	ire Num	ber of Reflow Cyc	les		
SnAgCu		C	U Alloy		3		260		С	30	second	ls 3		
omments														
ITENTION: MSL 3 Rat	ted item requires Bal	ke and Dr	ry Pack (after	electrical test)										
or more information reg	arding material com	position p	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	26.39	mg		Misc.	proprietary data		0.1003	mg
			Supplier	Silicon (Si)	7440-21-3		26.0285	mg
			Supplier	Aluminum (Al)	7429-90-5		0.2613	mg
Die Attach	2.2	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.825	mg
			Supplier	Ethylene Glycol	107-21-1		0.022	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.066	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.462	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.825	mg
maging Lens	25.2	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.26	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.26	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		1.26	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.26	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.126	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.26	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.26	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		17.514	mg
Lid Attach	1.45	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.145	mg
			Supplier	Filler (SiO2)	68909-20-6		0.145	mg
			Supplier	Other Additive Agents	Proprietary Data		0.145	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.435	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.58	mg
Mold Compound-Black	65.64	mg		Phenolic Resin	proprietary data		9.846	mg
			Supplier	Oxirane	39817-09-9		9.846	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.9692	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6564	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		42.0096	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.3128	mg
older Ball	26.34	mg	Supplier	Silver (Ag)	7440-22-4		0.7902	mg
			Supplier	Tin (Sn)	7440-31-5		25.4181	mg
			Supplier	Copper (Cu)	7440-50-8		0.1317	mg
Substrate and Solder Mask	38.5	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		8.1582	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6	0.5043	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	0.1271	mg
			Supplier	Acetophenone Derivative	Proprietary Data	0.7546	mg
			Supplier	Carbon Black (C)	1333-86-4	0.1271	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.1271	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	3.7422	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	1.5092	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	1.2936	mg
			Supplier	Copper (Cu)	7440-50-8	18.2528	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	3.9039	mg
Wire Bond - Au	0.28	mg	Supplier	Gold (Au)	7440-57-5	0.28	mg